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PATENT  
Docket No. 20059/PIA31205

**IN THE UNITED STATES PATENT  
AND TRADEMARK OFFICE**

Applicant(s):

**OH, Sang Jun**

U.S. Serial No.: 10/764,905

For: "Methods for Forming an Air  
Gap in a Semiconductor Metal Line  
Manufacturing Process"


Filed: January 26, 2004

Group Art Unit: 1756

Examiner: Not yet Assigned

) I hereby certify that this paper and the  
) documents referred to as enclosed  
) therewith are being deposited with the  
) United States Postal Service as first  
) class mail, postage prepaid, in an  
) envelope addressed to Commissioner  
) for Patents, P.O. Box 1450,  
) Alexandria, Virginia 22313-1450 on  
) this date:

**June 8, 2005**

)   
) James A. Flight  
) Attorney for Applicant(s)  
) Registration No. 37,622

**STATUS LETTER**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

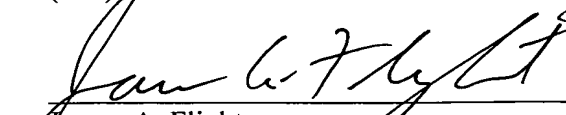
Kindly advise when an Office action can be expected in the above-referenced  
matter.

Respectfully submitted,

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Chicago, Illinois 60606  
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**June 8, 2005**

By:

  
James A. Flight  
Registration No.: 37,622